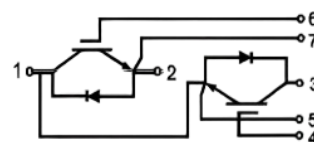


62mm Standard Housing IGBT Mouldle

DESCRIPTION

VCES=1200V, Ic=400A, VCE(sat)=2.2V for a 100°C junction operation temperature, the module accommodates a Half bridge configuration of Trench-Field Stop IGBT and matching emitter controlled diodes.



FEATURES

- Low collector to emitter saturation voltage
- Switching-Loss rating includes all "tail" losses
- Optimized for Fast Switching

APPLICATIONS

- Uninterruptible Power Supply
- Induction Heating
- High Power Converters
- Electric welding machine

MAXIMUM RATED VALUES(IGBT Inverter)

Absolute Maximum Ratings(Tj=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Value	Unit
V _{CE} S	Collector to Emitter Voltage		1200	V
V _{GE} S	Continuous Gate to Emitter Voltage		±20	V
I _c	Continuous Collector Current	T _c =100°C	400	A
		T _c =25°C	800	A
I _{cM}	Pulse Collector Current	tp=1ms	800	A
P _d	Maximum Power Dissipation (IGBT)	T _c =25°C, T _j =175°C	1666	W

MAXIMUM RATED VALUES (Diode Inverter)

Absolute Maximum Ratings(Tr=25°C unless otherwise noted)

V _{RRM}	Repetitive peak reverse voltage		1200	V
I _p	Diode Continuous Forward Current	T _c =100°C	400	A
I _{FM}	Peak FWD Current Repetitive	tp=1ms	800	A

ELECTRICAL CHARACTERISTICS VALUES(IGBT)

Static characteristics (Tj=25°C)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VGE(th)	Gate-Emitter Threshold Voltage	Ic=1mA, VcE=VGE, Tj=25°C	4.5	5.5	6.5	V
VcE(sat)	Collector-Emitter Saturation Voltage	Ic=400A, VGE=15V, Tj=25°C		2.2		V
		Tj=150°C		2.5		
IcES	Collector-Emitter Leakage Current	VGE=0V, VcE=VcEs, Tj=25°C			1.0	mA
IGES	Gate-Emitter Leakage Current	VGE=±20V, VcE=0V, Tj=25°C	-100		100	nA
Cies	Input Capacitance	VcE=25V, VGE=0V, f=1MHz		39.6		pF
Cres	Reverse transfer Capacitance			0.92		
Rgint	Internal gate resistor			0.2		Ω

Switching Characteristics

td(on)	Turn-on Delay Time	Vcc=600V, Ic=400A, VGE=±15V, L=525uH, Rg=10Ω	Tj=25°C		109		ns
			TJ=150°C		94		
tr	Rise Time		Tj=25°C		141		ns
			Tj=150°C		150		
td(off)	Turn-off Delay Time		TJ=25°C		472		ns
			Tj=150°C		500		
tf	Fall Time		Tj=25°C		95		ns
			TJ=150°C		114		
Eon	Turn-on Switching Loss		Tj=25°C		55.2		mJ
			TJ=150°C		74		
Eoff	Turn-off Switching Loss	TJ=25°C		25.2		mJ	
		TJ=150°C		30.4			
ReJC	Junction-To-Case(IGBT)				0.09		K/W

ELECTRICAL CHARACTERISTICS VALUES(DIODE)

Static characteristics (Tj=25°C)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
		Tj=25°C		2.8		

VFM	Forward Voltage	I=400A,V _{GE} =0V	T _j =150°C		2.3		V
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Switching Characteristics

I _r	Peak Reverse Recovery Current	I _p =400A, V _{cc} =600V, V _{GE} =-15V, L=525uH, R _g =10Ω	T=25°C		110		A
			T _j =150°C		190		
Q	Reverse Recovery Charge		T _z =25°C		14.2		μC
			T=150°C		39		
E _{rec}	Reverse Recovery Energy		T _j =25°C		3.8		mJ
			T=150°C		12.0		
RoJC	Junction-To-Case Diode				0.15		K/W

Module Characteristics

Viso	Isolation Voltage	f=50Hz,t=1min	4000			V
T	Maximum Junction Temperature				175	°C
TJoP	Maximum Operating Junction Temperature Range		-40		+150	°C
Tstg	Storage Temperature		-40		+150	°C
Recs	Case-To-Sink(Conductive Grease Applied)			0.01		K/W
M	Power Terminals Screw:M6		2.5		5.0	N · m
M	Mounting Screw:M6		3.0		5.0	N · m
G	Weight			320		g

CHARACTERISTICS DIAGRAMS

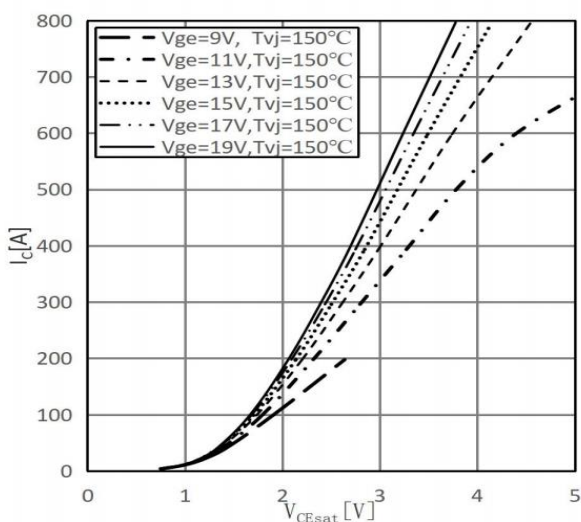


Fig.1 output characteristic IGBT Inverter (typical)

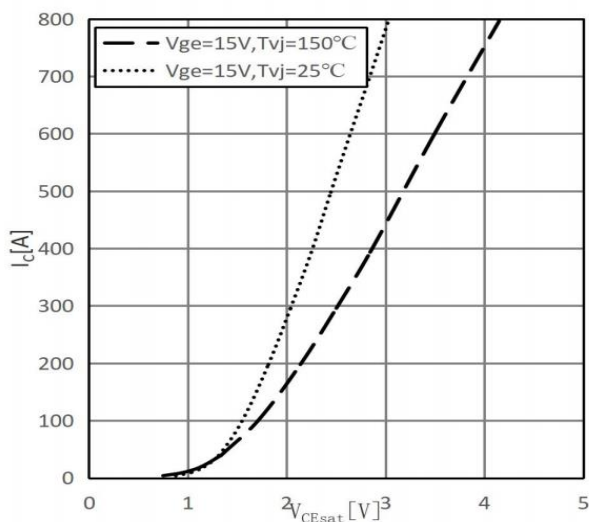


Fig.2 output characteristic IGBT Inverter (typical)

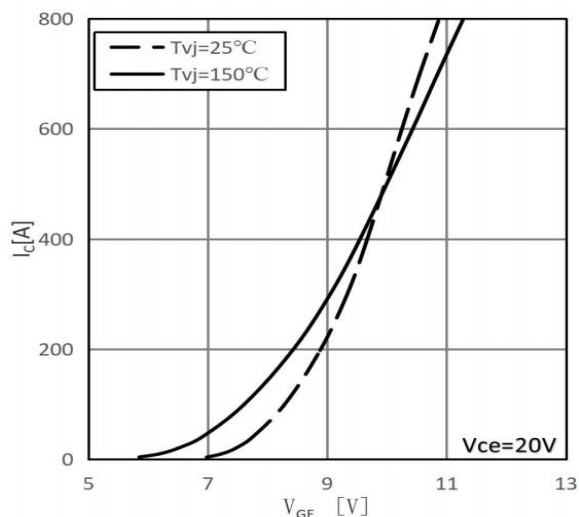


Fig.3 transfer characteristic IGBT Inverter (typical)

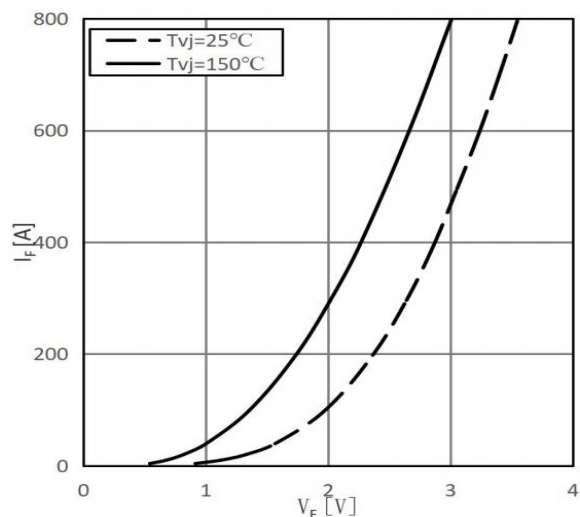


Fig.4 forward characteristic of Diode, Inverter (typical)

$V_{CC}=600\text{V}$, $V_{CE}=\pm 15\text{V}$
 $R_G=10\Omega$

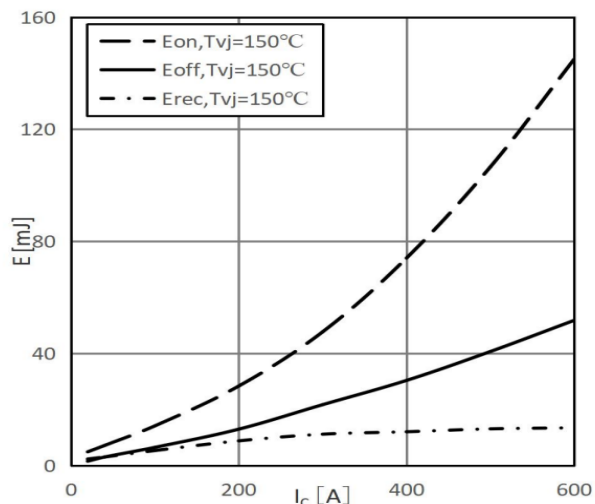


Fig.5 switching losses IGBT Inverter (typical)

$V_{CC}=600\text{V}$, $V_{CE}=\pm 15\text{V}$
 $I_c=400\text{A}$

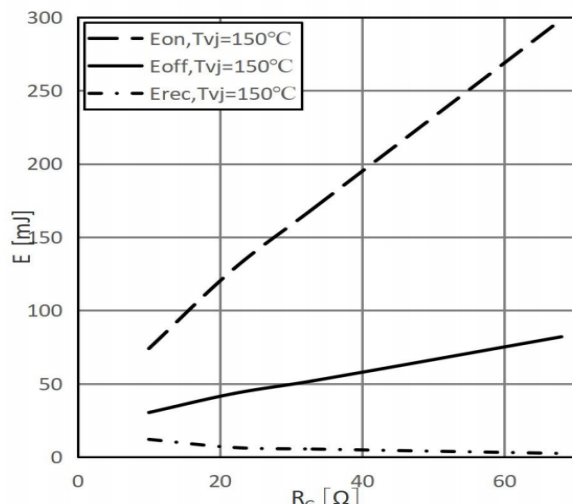


Fig.6 switching Losses vs. Gate Resistance (Typical)

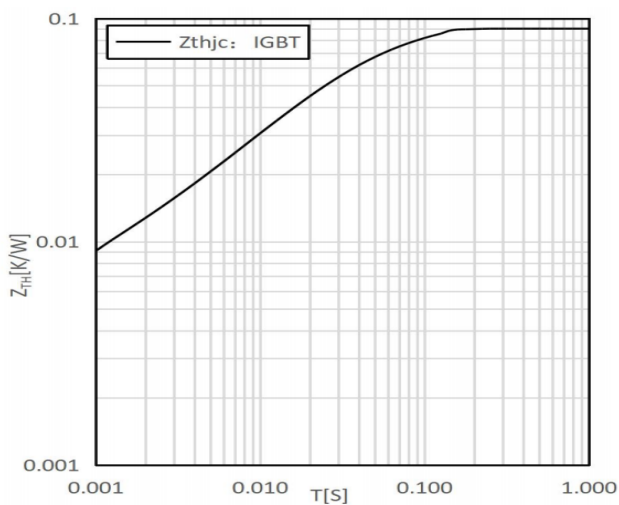


Fig.7 Transient thermal impedance IGBT

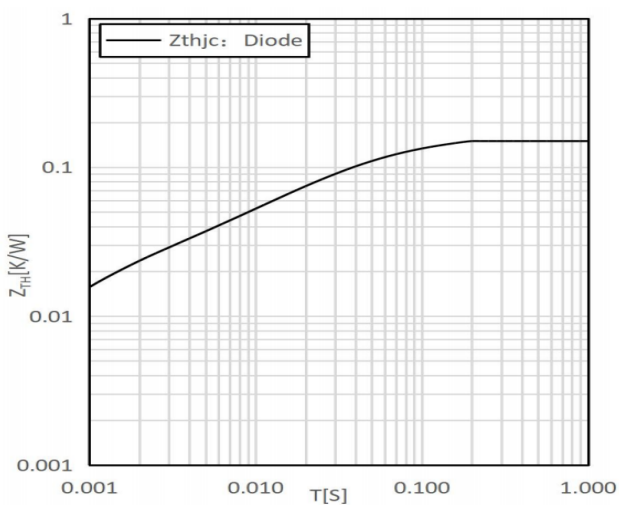
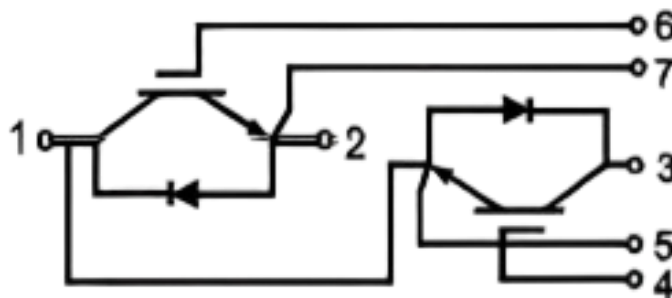
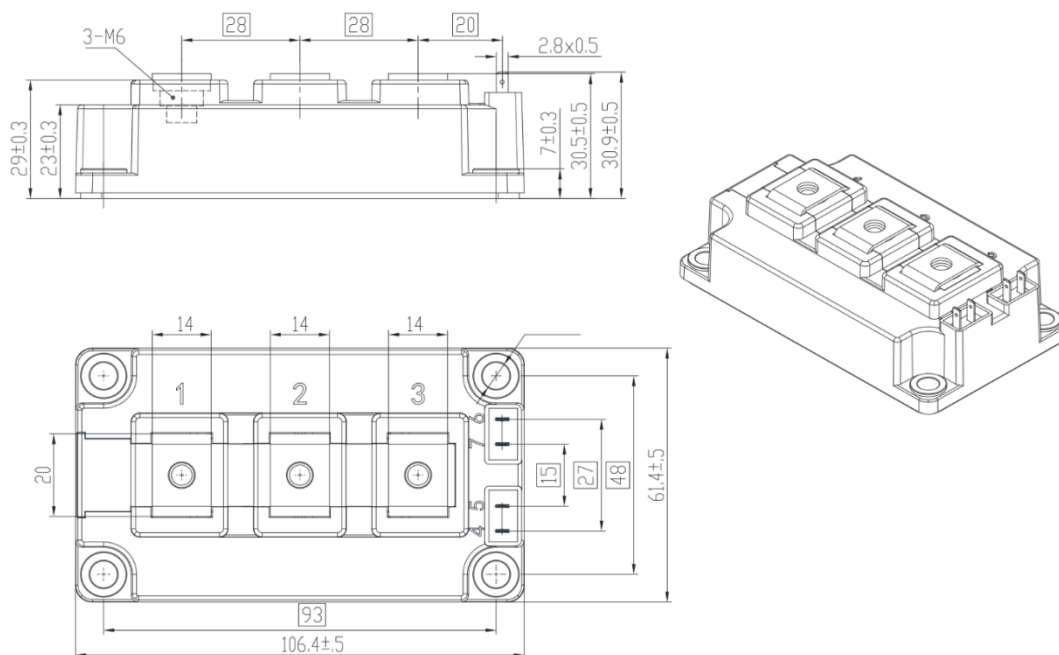


Fig.8 Transient thermal impedance Diode

CIRCUIT DIAGRAM



PACKAGE OUTLINES



NOTICE

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- 2) Implement redundancy, fire-prevention measures, and malfunction prevention protocols;
- 3) Mitigate risks of accidents, fires, or societal damages resulting from product use.
- 4) Designers must ensure Hypersemi products operate strictly within specified parameters defined in the latest product specifications.

Date of change	Rev #	Revise content
20222/4/06	A/0	First edition release